

# DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATION

☒ Original    ☐ Supplemental    ☐ Substitute    ☐ PCT    ☐ Design

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

**TITLE:            METHOD OF ENCAPSULATING SEMICONDUCTOR DEVICES ON A PRINTED CIRCUIT BOARD, AND A PRINTED CIRCUIT BOARD FOR USE IN THE METHOD**

of which is described and claimed in:

- ☒ the attached specification, *or*
- ☐ the specification in the application Serial No. \_\_\_\_\_ filed \_\_\_\_\_, and with amendments through \_\_\_\_\_ (if applicable), *or*
- ☐ the specification in International Application No. \_\_\_\_\_ filed \_\_\_\_\_, and as amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understand the content of the above-identified specification, including the claims, as amended by any amendment(s) referred to above.

I acknowledge my duty to disclose information of which I am aware which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United State Code, §119 (and §172 if this application is for a Design) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application n which priority is claimed:

COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
Korea	2003-15394	March 12, 2003	Yes

I hereby claim the benefit under Title 35, United States code, §120 and §119(e) of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION SERIAL NO.	U.S. FILING DATE	STATUS: PATENTED, PENDING, ABANDONED

And I hereby appoint Adam C. Volentine, Reg. No. 33289 and William S. Francos, Reg. No. 38,456, and the firm of **VOLENTINE FRANCOS, P.L.L.C.**, jointly and severally, attorneys to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith.

I hereby authorize the U.S. attorneys named herein to accept and following instructions from **Y.P. LEE, MOCK & PARTNERS** as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

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FULL NAME OF 4TH INVENTOR	FAMILY NAME		FIRST GIVEN NAME		SECOND GIVEN NAME	
	CITY		STATE OR COUNTRY		COUNTRY OF CITIZENSHIP	
RESIDENCE & CITIZENSHIP	CITY		STATE OR COUNTRY		COUNTRY OF CITIZENSHIP	
POST OFFICE ADDRESS	ADDRESS		CITY CODE		STATE OR COUNTRY ZIP	
FULL NAME OF 5TH INVENTOR	FAMILY NAME		FIRST GIVEN NAME		SECOND GIVEN NAME	
	CITY		STATE OR COUNTRY		COUNTRY OF CITIZENSHIP	
RESIDENCE & CITIZENSHIP	CITY		STATE OR COUNTRY		COUNTRY OF CITIZENSHIP	
POST OFFICE ADDRESS	ADDRESS CODE		CITY		STATE OR COUNTRY ZIP	
FULL NAME OF 6TH INVENTOR	FAMILY NAME		FIRST GIVEN NAME		SECOND GIVEN NAME	
	CITY		STATE OR COUNTRY		COUNTRY OF CITIZENSHIP	
RESIDENCE & CITIZENSHIP	CITY		STATE OR COUNTRY		COUNTRY OF CITIZENSHIP	
POST OFFICE ADDRESS	ADDRESS CODE		CITY		STATE OR COUNTRY ZIP	

I further declare that all statements made herein of my own knowledge are true, and that all statements on information and believe are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

1<sup>st</sup> Inventor Sang-Hyeop LEE Date: September 1, 2003  
Sang-Hyeop LEE

2<sup>nd</sup> Inventor Hee-Kook CHOI Date: September 1, 2003  
Hee-Kook CHOI

3<sup>rd</sup> Inventor \_\_\_\_\_ Date: \_\_\_\_\_

4<sup>th</sup> Inventor \_\_\_\_\_ Date: \_\_\_\_\_

5<sup>th</sup> Inventor \_\_\_\_\_ Date: \_\_\_\_\_

6<sup>th</sup> Inventor \_\_\_\_\_ Date: \_\_\_\_\_

Applicant Reference No. IC2002-11-006-1 US0 Atty Docket No. SEC.1065